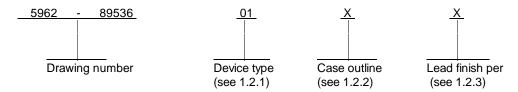
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1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit	Access time
01	(see 6.6)	1k X 9-bit parallel FIFO	120 ns
02	(see 6.6)	1k X 9-bit parallel FIFO	80 ns
03	(see 6.6)	1k X 9-bit parallel FIFO	65 ns
04	(see 6.6)	1k X 9-bit parallel FIFO	40 ns
05	(see 6.6)	1k X 9-bit parallel FIFO	30 ns
06	(see 6.6)	1k X 9-bit parallel FIFO	20 ns

1.2.2 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835, and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
X	CDIP3-T28 or GDIP4-T28	28	Dual-in-line package
Υ	CDIP1-T28 or GDIP2-T28	28	Dual-in-line package
Z	GDFP2-F28	28	Flat package, configuration 1
U	CQCC1-N32	32	Rectangular leadless chip carrier package

-0.5 V dc to +7.0 V dc

1.2.5 <u>Lead finish</u>. The lead finish shall be as specified in MIL-M-38510. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

DC output current	50 mA -65°C to +150°C 1.0 W +260°C See MIL-STD-1835
Junction temperature (T _J)	+150°C <u>1</u> /
Supply voltage range (V_{CC})	4.5 V dc to 5.5 V dc 2.2 V dc +0.8 V dc <u>2</u> / -55° C to +125° C

Terminal voltage with respect to ground

- 1/ Maximum junction temperature may be increased to + 175°C during burn-in and steady state life.
- 2/ 1.5 V undershoots are allowed for 10 ns once per cycle.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-89536
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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, bulletin, and bulletin</u>. Unless otherwise specified, the following specifications, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATIONS

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specifications, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
 - 3.2.3 Truth table(s). The truth table(s) shall be as specified on figure 2.
- 3.2.4 <u>Die overcoat</u>. Polyimide and silicone coatings are allowable as an overcoat on the die for alpha particle protection provided that each coated microcircuit inspection lot (see MIL-M-38510) shall be subjected to and pass the internal moisture content test, (test method 1018 of MIL-STD-883), the frequency of the internal water vapor testing may not be decreased unless approved by the preparing activity.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

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TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol	Conditions -55° C ≤ T _C ≤ +125° C	Group A subgroups	Device types	Lir	nits	Unit
		V _{SS} = 0 V,4.5 V ≤ V _{CC} ≤ 5.5 V unless otherwise specified			Min	Max	
Input leakage current	I _{LI}	$0.0 \text{ V} \leq V_{IN} \leq V_{CC}$	1, 2, 3	All	-10	10	μ A
Output leakage current	I _{LO}	$0.0 \text{ V} \leq \text{V}_{OUT} \leq \text{V}_{CC}, \ \overline{\text{R}} \geq \text{V}_{IH}$	1, 2, 3	All	-10	10	
Output low voltage	V _{OL}	V _{CC} = 4.5 V, I _{OL} = 8.0 mA V _{IL} = 0.8 V, V _{IH} = 2.2 V	1, 2, 3	All		0.4	V
Output high voltage	V _{OH}	V _{CC} = 4.5 V, I _{OH} = -2.0 mA V _{IL} = 0.8 V, V _{IH} = 2.2 V	1, 2, 3	All	2.4		
Operating supply current	I _{CC1}	f = maximum, outputs open V_{CC} = 5.5 V_{RS} = FL/RT = V_{IH}	1, 2, 3	01-03		100	mA
		f = 20 MHz, outputs open V _{CC} = 5.5 V		04-06		140	IIIA
Standby power supply current	I _{CC2}	$\overline{R} = \overline{W} = \overline{RS} = \overline{FL} / \overline{RT} = V_{IH}$ Output open, $f = 0$ MHz	1, 2, 3	01-03		15	mA
Current		Output open, I = 0 MHZ		04-06		20	IIIA
Power down current	I _{CC3}	All inputs = V _{CC} -0.2 V, Outputs open, f = 0 MHz	1, 2, 3	All		900	μΑ
Input capacitance	C _{IN}	V _I = 0 V, f = 1.0 Mhz, T _A = +25°C, see 4.3.1c	4	All		8.0	pF
Output capacitance	C _{OUT}	$V_I = 0 \text{ V}, f = 1.0 \text{ Mhz},$ $T_A = +25^{\circ}\text{C}, \text{ see } 4.3.1\text{c}$	4	All		8	pF
Functional test		See 4.3.1d	7, 8A, 8B	All			

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SIZE A		5962-89536
	REVISION LEVEL A	SHEET 4

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device types	Lir	nits	Unit
		$-55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C}$ $\text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V}$ unless otherwise specified			Min	Max	
				01	140		ns
Read cycle time	t _{RC}	C _L = 30 pF See figure 4 and 5		02	100		
		See figure 4 and 5	9, 10, 11	03	80		
			3, 10, 11	04	50		
				05	40		
				06	30		
				01		120	ns
Access time	t _A			02		80	
			9, 10, 11	03		65	
			3, 10, 11	04		40	
				05		30	
				06		20	1
				01, 02	20		ns
Read recovery time	t _{RR}		9, 10, 11	03	15		
				04-06	10		
				01	120		ns
Read pulse width	t _{RPW}			02	80		
			9, 10, 11	03	65		
		0, 10, 11	04	40		7	
				05	30		
				06	20		
				01-03	10		ns
Read pulse low to data bus at low Z	^t RLZ <u>1</u> /		9, 10, 11	04-06	5		

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REVISION LEVE

 ${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{ - Continued.}$

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device types	Lir	mits	Unit
		$ \begin{array}{c} -55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C} \\ \text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} $			Min	Max	
		C _L = 30 pF See figure 4 and 5		01, 02	20.0		ns
Write pulse high to data bus at low Z	t _{WLZ}	See figure 4 and 5	9, 10, 11	03	15		
bus at low Z	<u>1/ 2</u> /		9, 10, 11	04	10		
				05, 06	5.0		
Data valid from read pulse high	t _{DV}		9, 10, 11	All	5.0		ns
Read pulse high to data bus at high Z			9, 10, 11	01		35	ns
	^t RHZ			02, 03		30	
	<u>1</u> /			04		25	
				05		20	
				06		15	
144.56	ļ		ļ	01	140		ns
Write cycle time	^t wc			02	100		
			9, 10, 11	03	80		
				04	50		
				05	40		
				06	30		
Write pulse width	1.			01	120		ns
write puise wiatri	twpw			02	80		
			9, 10, 11	03	65		
				04	40		
				05	30		-
				06	20		
Write recovery time	two		9, 10, 11	01, 02	20		ns
Time tootory unio	t _{WR}		3, 10, 11	03	15		-
				04-06	10		

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 ${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{ - Continued.}$

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device types	Lir	mits	Unit
		$ \begin{array}{c} -55^{\circ}\text{C} \leq \text{T}_{C} \leq +125^{\circ}\text{C} \\ \text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} \text{ substitution} $			Min	Max	
		C _L = 30 pF, See figure 4 and 5		01, 02	40		ns
Data setup time	t _{DS}	See figure 4 and 5	0 40 44	03	30		
		9, 10, 11	04	20			
				05	18		
				06	12		7
Data hold time	t _{DH}			01-03	10		ns
		9, ′	9, 10, 11	04-06	0.0		
				01	140		ns
Reset cycle time	t _{RSC}			02	100		
			9, 10, 11	03	80		
			9, 10, 11	04	50		
				05	40		
				06	30		
				01	120		ns
Reset pulse width	t _{RS}		9, 10, 11	02	80		
				03	65		
			9, 10, 11	04	40		
				05	30		
				06	20		
				01, 02	20		ns
Reset recovery time	ime t _{RSR}	9, 10, 11	03	15		7	
				04-06	10		7

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 ${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{ - Continued.}$

Test	Symbol	Symbol Conditions G -55° C \leq T _C \leq +125° C sub	Group A subgroups	Device types	Lir	nits	Unit
	$ \begin{array}{c} -55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C} \\ \text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} $			Min	Max		
		C _L = 30 pF See figure 4 and 5		01	120		ns
Reset setup time	t _{RSS}	See figure 4 and 5		02	80		
	<u>1</u> /	/	9, 10, 11	03	65		
			0, 10, 11	04	40		
				05	30		
				06	20		
				01	140		ns
Retransmit cycle time	t _{RTC}			02	100		
			9, 10, 11	03	80		
			0, 10, 11	04	50		
				05	40		
				06	30		
				01	120		ns
Reytransmit pulse width	t _{RT}			02	80		
			9, 10, 11	03	65		
			0, 10, 11	04	40		
				05	30		
				06	20		
				01, 02	20		ns
Retransmit recovery time	t _{RTR}		9, 10, 11	03	15		
				04-06	10		
				01		140	ns
Reset to empty flag low t _{EFL}	t _{EFL}			02		100	
			9, 10, 11	03		80	_
			3, .0, .1	04		50	_
				05		40	
				06		30	I

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TABLE I. <u>Electrical performance characteristics</u> - C9ontinued.

Test	Symbol	Conditions -55° C ≤ T _C ≤ +125° C	Group A subgroups	Device types	Lir	mits	Unit
		$ \begin{array}{c} -55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C} \\ \text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} $	3 1	,,,	Min	Max	
		C _L = 30 pF See figure 4 and 5		01- 03		60	ns
Read low to empty flag low	t _{REF}	See figure 4 and 5	9, 10, 11	04, 05		30	
				06		20	
	Ţ			01 - 03		60	ns
Read high to full flag high	t _{REF}		9, 10, 11	04		35	
			9, 10, 11	05		30	
				06		20	
			9, 10, 11	01- 03		60	ns
Write high to empty flag	tweF			04		35	
high				05		30	
				06		20	
				01- 03		60	ns
Write low to full flag low	twff		0 10 11	04		35	
			9, 10, 11	05		30	
				06		20	
				01		140	ns
Reset to half full and full flag high	t _{HFH} ,			02		100	
	^t FFH	FH	9, 10, 11	03		80	
			, , , , , , ,	04		50	
				05		40	
				06		30	

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 ${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{ - Continued.}$

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device types	Limits		Unit
		$ \begin{array}{c} -55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C} \\ \text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} $			Min	Max	
		C _L = 30 pF See figure 4 and 5		01		120	ns
Read/ write to \overline{XO} low	^t xoL	See figure 4 and 5		02		80	
			9, 10, 11	03		65	
			0, 10, 11	04		40	
				05		30	
		」 L		06		20	
Read/ write to \overline{XO} high			9, 10, 11	01		120	ns
	^t xoh			02		80	
				03		65	
			0, 10, 11	04		40	
				05		30	
			06		20		
				01	120		ns
XI pulse width	t _{XI}			02	80		
			9, 10, 11	03	65		
			0, 10, 11	04	40		
				05	30		
				06	20		
XI recovery time	t _{XIR}		9, 10, 11	All	10		ns
,	AIR		, -, -	01- 03	15		ns
XI setup time	t _{XIS}		9, 10, 11	04 - 06	10		7

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 ${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{ - Continued.}$

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Group A subgroups	Device types	Lir	nits	Unit
		$ \begin{array}{c} -55^{\circ}C \leq T_{C} \leq +125^{\circ}C \\ V_{SS} = 0 \text{ V}, 4.5 \text{ V} \leq V_{CC} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} $			Min	Max	
		C _L = 30 pF See figure 4 and 5		01	120		ns
Retransmit setup time	t _{RTS}	See figure 4 and 5		02	80		
			9, 10, 11	03	65		
	_1/		, ,	04	40		
				05	30		
				06	20		
				01	120		ns
Read pulse width after EF high	t _{RPE}		9, 10, 11	02	80		
				03	65		
				04	40		
				05	30		
				06	20		
				01		140	ns
Write low to half-full flag low	t _{WHF}			02		100	
			9, 10, 11	03		80	
			3, 13, 11	04		50	
				05		40	
				06		30	
				01		140	ns
Read high to half-full flag	t _{RHF}			02		100	
high			9, 10, 11	03		80	
			2,,	04		50	
				05		40	
				06		30	

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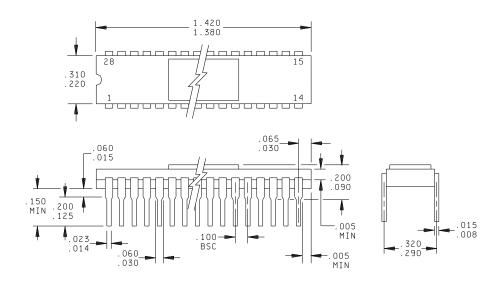
${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{ - Continued.}$

Test	Symbol	Conditions -55° C ≤ T _C ≤ +125° C	Group A subgroups	-	Group A subgroups	Device types	Lir	nits	Unit
		$ \begin{array}{c} -55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C} \\ \text{V}_{\text{SS}} = 0 \text{ V}, 4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V} \\ \text{unless otherwise specified} \end{array} $			Min	Max			
		C _L = 30 pF See figure 4 and 5		01	120		ns		
Write pulse width after EF			9, 10, 11	02	80				
high				03	65				
		0, 10, 11	04	40					
				05	30				
				06	20				

- $\underline{1}\!/$ If not tested, shall be guaranteed to the limits specified in table I.
- 2/ Only applies to read data flow-through mode.

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Inches	mm	Inches	mm
		ī	
.005	.13	.125	3.18
.008	.20	.150	3.81
.014	.36	.200	5.08
.015	.38	.220	5.59
.023	.58	.290	7.37
.030	.76	.310	7.87
.060	1.52	.320	8.13
.065	1.65	1.380	35.05
.090	2.29	1.420	36.07
.100	2.54		

NOTES;

- Dimensions are in inches. Metric equivalents are given for general information only.

FIGURE 1. Case outline X .

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Device types	All		
Case outlines	X and Y	Z	
Terminal number	Termina	al symbol	
1 2 3 4 5 6 7 8 9	W ₈ ₃ ₂ ₂ ₂ ₃ ₄ ₅ ₅ ₅ ₆ ₇	NC W D ₈ D ₃ D ₂ D ₁ D ₀ X I FF Q ₀	
11 12 13 14 15 16 17 18 19 20	$\begin{array}{c}Q_2\\Q_3\\Q_8\\\text{GND}\\\overline{\text{R}}\\Q_4\\Q_5\\Q_6\\Q_7\\\text{XO/HF}\end{array}$	Q ₁ NC Q ₂ Q ₃ Q ₈ D NC R Q ₄ Q ₅	
21 22 23 24 25 26 27 28 29 30	EF RS FL/RT D ₇ D ₆ D ₅ D ₄ VCC 	$\begin{array}{c} Q_6\\ Q_7\\ XO/HF\\ EF\\ RS\\ FL/RT\\ NC\\ D_7\\ D_6\\ D_5\\ \end{array}$	
31 32		$^{D_4}_{CC}$	

NC = no connection

FIGURE 2. <u>Terminal connections</u>.

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Reset and retransmit single device configuration/width expansion mode

Mode	Inputs		Internal	Outputs				
Mode	RS	RT	ΧT	Read pointer	Write pointer	ĒF	FF	ĦF
Reset Retransmit Read/Write	0 1 1	X 0 1	0 0 0	Location zero Location zero Increment <u>1</u> /	Location zero Unchanged Increment 1/	0 X X	1 X X	1 X X

1/ Poiter will increment if flag is high.

Reset and first load depth expansion/compound expansion mode

	Inputs			Interna	Outputs		
Mode	RS	FL	ΧT	Read pointer	Write pointer	EF	FF
Reset first device Reset all other devices Read / write	0 0 1	0 1 X	<u>1</u> / <u>1</u> / <u>1</u> /	Location zero Location zero X	Location zero Location zero X	0 0 X	1 1 X

 $\underline{1}$ / $\overline{X}\overline{I}$ is connected to \overline{XO} of previous device.

NOTE: \overline{RS} = Reset input, $\overline{FL}/\overline{RT}$ = First load / retransmit

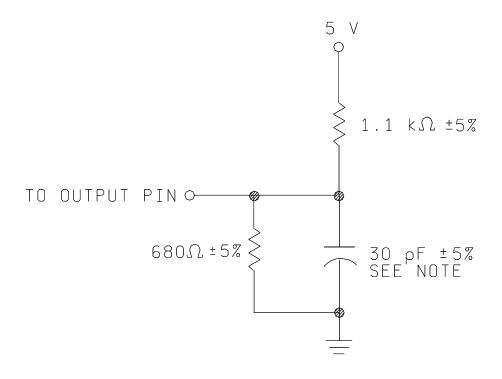
 $\overline{\text{EF}} = \text{Empty flag output}, \ \overline{\text{FF}} = \text{Full flag output}, \ \overline{\text{X I}} = \text{Expansion input},$ and $\overline{\text{HF}} = \text{Half-full flag output}$

0 = Low level voltage

1 = High level voltage X = Don't care

FIGURE 3. Truth tables.

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NOTE: C_L include scope and jig capacitance

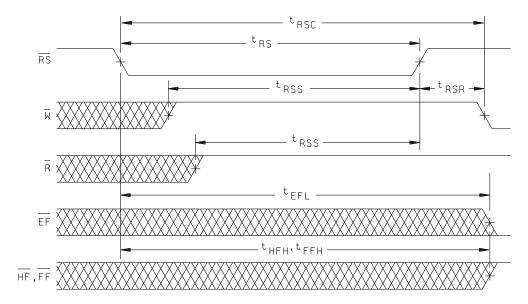
AC test conditions

Input pulse levels Input rise and fall times Input timing reference levels	GND to 3.0 V ≤5 ns 1.5 V
Output reference levels	1.5 V

FIGURE 4. Output load circuit and ac test conditions.

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RESET TIMING SEE NOTES 1 AND 2



ASYNCHRONOUS WRITE AND READ OPERATION TIMING

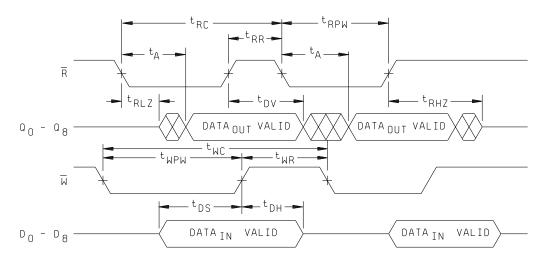
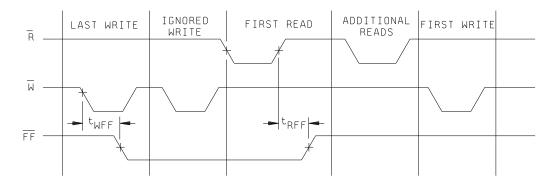


FIGURE 5. Timing waveforms.

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FULL FLAG FROM LAST WRITE TO FIRST READ



EMPTY FLAG FROM LAST READ TO FIRST WRITE

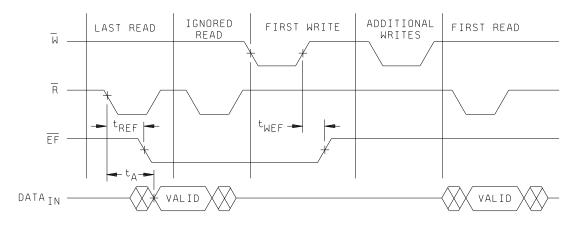


FIGURE 5. <u>Timing waveforms</u> - Continued.

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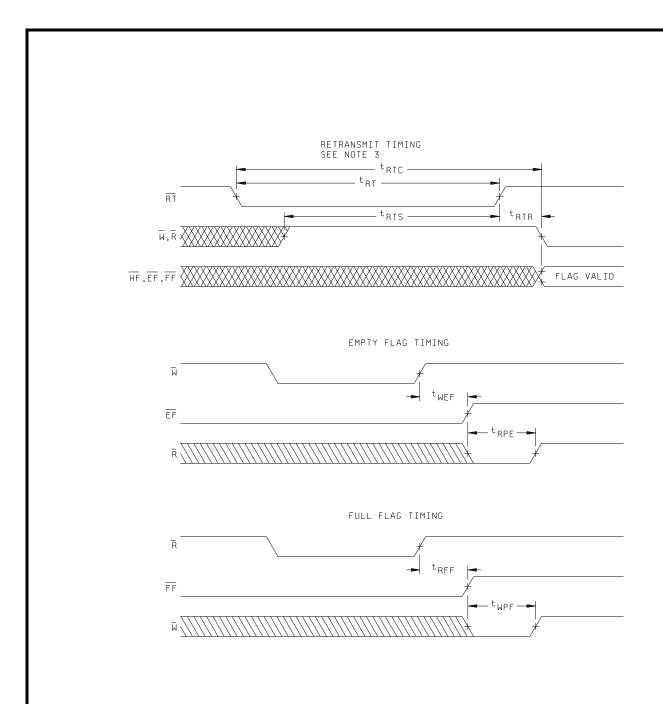
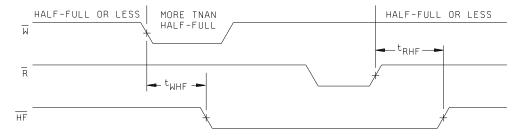


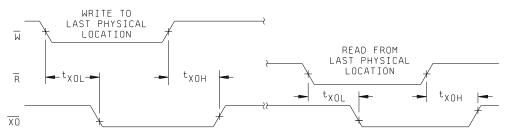
FIGURE 5. <u>Timing waveforms</u> - Continued.

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HALF-FULL FLAG TIMING



EXPANSION OUT TIMING



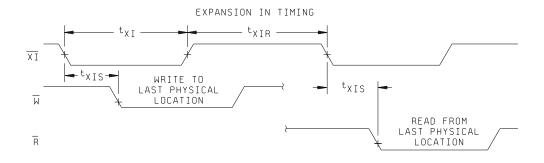
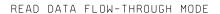


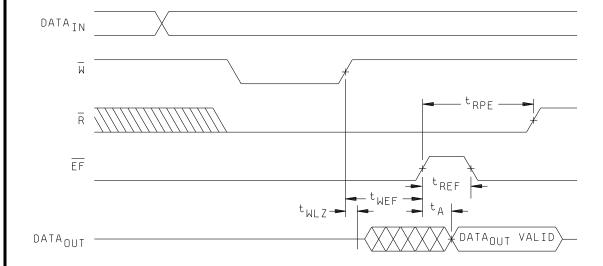
FIGURE 5. <u>Timing waveforms</u> - Continued.

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WRITE DATA FLOW-THROUGH MODE

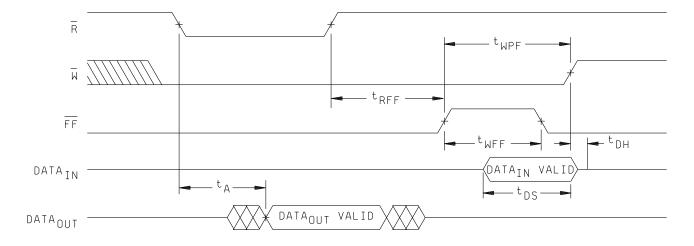


FIGURE 5. Timing waveforms - Continued.

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- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ} C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11
Group A test requirements (method 5004)	1, 2, 3, 4**, 7, 8A, 8B, 9, 10, 11
Group C and D end-point electrical parameters (method 5005)	2, 3, 7, 8A, 8B

- * PDA applies to subgroups 1.
- ** See 4.3.1c.

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- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
- 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - Subgroup 4 (C_{IN} measurement) shall be measured only for the initial test and after process or design changes which
 may affect input capacitance.
 - d. Subgroups 7 and 8 shall include verification of the truth table.
- 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ} C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for original equipment manufacturer application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 23

STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE: 93-09-17

Approved sources of supply for SMD 5962-89536 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standardized military drawing PIN	Vendor CAGE number	Vendor similar PIN <u>1</u> /
5962-8953601XX	61772 OHGZ7	IDT7202LA120TDB MM1P-67202-55MB
5962-8953601YX	61772	IDT7202LA120DB
5962-8953601ZX	61772	IDT7202LA120XEB
5962-8953601UX	61772 OHGZ7	IDT7202LA120LB MM4J-67202-55MB
5962-8953602XX	61772 OHGZ7	IDT7202LA80TDB MM1P-67202-55MB
5962-8953602YX	61772	IDT7202LA80DB
5962-8953602ZX	61772	IDT7202LA80XEB
5962-8953602UX	61772 OHGZ7	IDT7202LA80LB MM4J-67202-55MB
5962-8953603XX	61772 OHGZ7	IDT7202LA65TDB MM1P-67202-45MB
5962-8953603YX	61772	IDT7202LA65DB
5962-8953603ZX	61772	IDT7202LA65XEB
5962-8953603UX	61772 OHGZ7	IDT7202LA65LB MM4J-67202-45MB
5962-8953604XX	61772 OHGZ7	IDT7202LA40TDB MM1P-67202-35MB
5962-8953604YX	61772	IDT7202LA40DB
5962-8953604ZX	61772	IDT7202LA40XEB
5962-8953604UX	61772 OHGZ7	IDT7202LA40LB MM4J-67202-35MB
5962-8953605XX	61772	IDT7202LA30TDB
5962-8953605YX	61772	IDT7202LA30DB
5962-8953605ZX	61772	IDT7202LA30XEB
5962-8953605UX	61772	IDT7202LA30LB
5962-8953606XX	61772	IDT7202LA20TDB
5962-8953606YX	61772	IDT7202LA20DB
5962-8953606ZX	61772	IDT7202LA20XEB
5962-8953606UX	61772	IDT7202LA20LB

<u>1/Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE

number

61772

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OHGZ7

Matra-MHS

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The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.